



Downloaded from Elcodis.com electronic components distributor

	1 2	3 4
Propriete de c FCI. Droits de reproduction FCI.	 NOTES: Materials: Housing: High Temperature Thermoplastic , UL94V-0, Color/Nat Contact: Copper Alloy. Solderable Holddown: Copper Alloy. Specification: Product Spec: GS-12-240. Packaging Spec: GS-14-1010. Tin/Lead Plating Spec: Contact: Under Plated 50u" Min Nickel All Over, 100u" Min Tin/Lead in Solder Tail Area, Selective Gold Plating in Contact Area. Solderable Holddown: Under Plated 50u" Min Nickel, Plated 100u"Min Tin/Lead All Over. Lead-Free Plating Spec: Contact: Under Plated 50u" Min Nickel All Over, 100u" Min Pure Matte Tin in Solder Tail Area, Selective Gold Plating in Contact Area. Solderable Holddown: Under Plated 50u" Min Nickel, Plated 100u"Min Nickel, Note: Solderable Holddown: Under Plated 50u" Min Nickel, Plated 100u"Min Pure Matte Tin All Over, 100u" Min Pure Matte Tin in Solder Tail Area, Selective Gold Plating in Contact Area. Solderable Holddown: Under Plated 50u" Min Nickel, Plated 100u"Min Pure Matte Tin All Over. The Housing Will Withstand Exposure to 260°C Peak Temperature For 10 Seconds In A Convection, IR Or Vaper Phase Reflow Oven. This Product (10017963-XXXXLF) Meets the European Union Directive as Described in GS-22-008, Sub Clause 3.1. (2002/95/EC). 	tural. $\begin{array}{c} \hline \begin{array}{c} \hline \begin{array}{c} \hline \begin{array}{c} \hline \\ \hline $
perty of FCL. Copyright FCL. B	PACKAGING BLANK: PVC TRAY. T: TAPE & REEL. CONTACT AREA PLATING: D: 15u" GOLD. E: 30u" GOLD.	nat'l. code

Downloaded from **Elcodis.com** electronic components distributor